

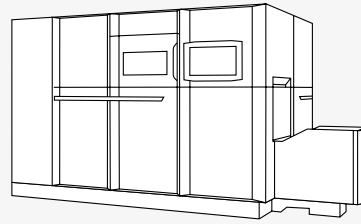


EOS P 500
The Automation-Ready
Manufacturing Platform for Laser Sintering
of Plastic Parts on an Industrial Scale

EOS P 500

Enabling maximum material flexibility

The innovative manufacturing platform produces high-quality components at the lowest cost-per-part. Thanks to clever hardware interfaces and accessories, the uptime of the EOS P 500 increases by up to 75% compared to predecessor systems and competition models.



- The innovative recoater, which applies and densifies material with a speed of up to 0,6 m/sec, as well as two powerful 70 watt lasers reduce cost-per-part by more than 30%.
- The new 3-stage filter unit and an intelligent thermo- and protective gas management ensure optimum process conditions.
- The system enables maximum material flexibility (incl. high performance polymers). Open software interfaces and user-friendly tools support application and material development.
- Extensive sensor technology plus optical monitoring enable excellent process monitoring to meet the requirements of the aerospace and automotive industries.
- With EOSYSTEM the machine is operated intuitively. EOSPRINT 2 enables software integration in CAD systems, e. g. NX™ from Siemens and via EOSCONNECT the connection to ERP systems. Thus the EOS P 500 supports a digital control of production.
- Automated interfaces and optimized accessories reduce the cycle time drastically and ensure building process of several days duration.

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Technical Data EOS P 500

* Exemplary build cycle: 5% packaging density
120 µm layer thickness

Building volume	500 x 330 x 400 mm (19.7 x 13 x 15.7 in)
Laser type	CO ₂ ; 2 x 70 W
Building rate	up to 6.6 l/h*
Layer thickness	120 µm
Precision optics	F-theta lens, surface module, high-speed scanner
Scan speed during build process	up to 2 x 10 m/sec (32.8 ft/s)
Power supply	400 V/100 A; max. power consumption 80 A
Dimensions (W x D x H)	3,400 x 2,100 x 2,100 mm (133.9 x 82.7 x 82.7 in)
Recommended installation space	min. 7.2 x 5.2 x 4.2 m (284 x 205 x 165 in)
Weight	approx. 7,000 kg (15,432 lb)

Software

EOSYSTEM, EOSPRINT 2, EOSPRINT Premium Module, EOSCONNECT, EOSTATE

Materials

PA 2200

Optional Accessories

Cooling station, IPCM P plus, unpacking and sieving station, blasting cabinet

